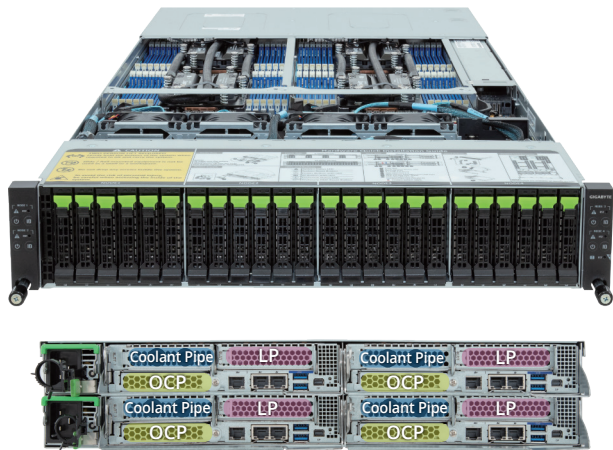


H273-Z80-LAN1

High Density Server - 2U 4-Node DP 24-Bay NVMe/SATA



Features

- 2U 4-node rear access liquid cooling solution
- Dual AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 24x 2.5" Gen4 NVMe/SATA/SAS hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface (optional)
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 2600W 80 PLUS Titanium redundant power supply

Application

HPC, HCI, Hybrid/Private Cloud Server

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D877 mm)	Power Supply	Dual 2600W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Motherboard	MZ83-HD0	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
CPU	AMD EPYC™ 9005/9004 Series Processors Dual processor per node, cTDP up to 400W	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Socket	8 x LGA 6096 (Socket SP5)	System Fans	4 x 80x80x38mm (18,300rpm)
Chipset	System on Chip	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Memory	12-Channel DDR5 RDIMM, 96 x DIMMs [EPYC 9005] RDIMM: Up to 6000 MT/s [EPYC 9004] RDIMM: Up to 4800 MT/s	Packaging Co17ntent	1 x H273-Z80-LAN1, 4 x CoolIT CPU cold plate loops, 1 x Mini-DP to D-Sub cable, 1 x 3-Section Rail kit Packaging Dimensions: w/ cold plate loops: 1185 x 705 x 409 mm w/o cold plate loops: 1176 x 709 x 322 mm
LAN	8 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Support NCSI function 4 x 10/100/1000 management LAN	Part Numbers	Barebone w/ cold plates: 6NH273Z80DR000LCN1* Barebone w/o cold plates: 6NH273Z80DZ000LCN1* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - M.2 expansion card - CMTP192: 9CMTTP192NR-00* - GIGABYTE CPU cold plate loop: 25H27-3Z80000-E06X (QPA:4) - GIGABYTE 2U4N manifold: 25H27-3Z80000-E07X (1 set per rack) - Motivair CPU cold plate loop: 25ST7-20000K-M4R (QPA:4) - CoolIT leak sensor board: 6NH273Z80S1000LAN11 (QPA: 4) - RMA packaging: 6NH273Z80SR-RMA-L100
Video	Integrated in ASPEED® AST2600 x 4 (4 x Mini-DP)		
Storage	Front hot-swap: 24 x 2.5" Gen4 NVMe/SATA/SAS *SAS card is required to support SAS drives. Optional internal M.2: 4 x M.2 (2280/22110)		
RAID	Require RAID add-in cards		
Expansion Slots	4 x LP PCIe Gen5 x16 slots 4 x OCP 3.0 PCIe Gen5 x16 slots		
Rear I/O	8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN		
Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s		
TPM	4 x TPM headers with SPI interface (Optional TPM2.0 kit: CTM010)		



Learn more at <https://www.GIGABYTE.com/enterprise>

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